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SHEET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

OMB No. 6514-0011(exp-4/94)

F0395ED-US

To the Honorable Commissioner of

100974321

attached original Documents or copy thereof.

1. Name of conveying party(ies):

Kenji Mieda
Heiji FukutakeAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: **Exedy Corporation**
Internal Address:Street Address: **1-1, Kidamotomiya 1-chome**
Neyagawa-shiCity: **Osaka**, Country: **Japan** Zip: **572-0822**Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ OtherExecution Date: **02/03/99**

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: **02/03/99**

A. Patent Application No.(s)

B. Patent No.(s)

Additional Application numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name:

Shinju Global IP Counselors, LLP

Internal Address:

02/23/1999 STHOMTD 00000048 09249298**03 FC:581****40.00 OP**Street Address: **1233 Twentieth Street, NW**
Suite 700City: **Washington State: D.C.** ZIP: **20036**6. Total number of applications and patents involved: **1**7. Total fee (37 CFR 3.41) ... **\$40.00**☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.***David L. Tarnoff**

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and document: **2**Mail documents to be recorded with required cover sheet Information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231PATENT
REEL: 9783 FRAME: 0227

ASSIGNMENT

[Executed in Japan]

WHEREAS, Kenji MIEDA, a citizen of Japan residing at 49-4, Hashiridani 2-chome, Hirakata-shi, Osaka 573-0063, Japan,

Heiji FUKUTAKE, a citizen of Japan residing at 1-18-9 Seifuso, Toyonaka-shi, Osaka 560-0041, Japan

hereinafter referred to as the Assignor(s), have invented certain new and useful improvements in

HEAT GATHERING DEVICE HAVING A REFLECTION PLATE ASSEMBLY

for which the Assignor(s) have executed an Application for United States Letters Patent on even date herewith,

AND WHEREAS, EXEDY Corporation having its principal place

of business at 1-1, Kidamotomiya 1-chome, Neyagawa-shi, Osaka 572-0822, Japan

(hereinafter referred to as the Assignee), is desirous of acquiring the entire right, title, and interest in and to said invention and said Application and in and to any Letters Patent or Patents, United States or foreign as indicated below, to be obtained therefor and thereon:

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is herewith acknowledged, the Assignor(s) sell, assign, and transfer, unto the Assignee, its successors, legal representatives and assigns, the entire right, title, and interest in the United States of America, and in all foreign countries including, but not limited to, the following countries,

Germany and China

in, to and under said improvements, and said Application, and all original, divisional, renewal, continuation, substitute, or reissue applications thereof, including the right to sue and recover for any past infringement, and all rights of priority from the filing of said Application; and the Assignor(s) hereby authorize and request the Commissioner of Patents and Trademarks to issue all Letters Patent on said improvements or resulting therefrom to said Assignee herein, as assignee of the entire interest therein, for the sole use and behoof of said Assignee, its successors, and assigns, to the full end of the term or terms for which Letters Patent or Patents may be granted.

Further, the Assignor(s) and their legal representatives, heirs, and assigns do hereby agree and covenant without further remuneration that they will communicate to said Assignee, its successors, legal representatives and assigns, any facts known to them respecting said improvements whenever requested, and will testify in any interferences or other legal proceeding in which any of said applications or Letters Patent may become involved, sign all lawful papers, execute and deliver all divisional, continuing, reissue and other applications for Letters Patent on said improvements and all assignments thereof to said Assignee or its legal representatives, successors, or assigns, make all rightful oaths and generally do everything necessary to assist said Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in the U.S. and said countries, the expenses incident to said applications to be borne and paid by said assignee.

IN TESTIMONY WHEREOF, the undersigned Assignor(s) have affixed their signatures.

This 3rd day of February, 1999 Signature Kenji Mieda

This 3rd day of February, 1999 Signature Heiji Fukutake

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